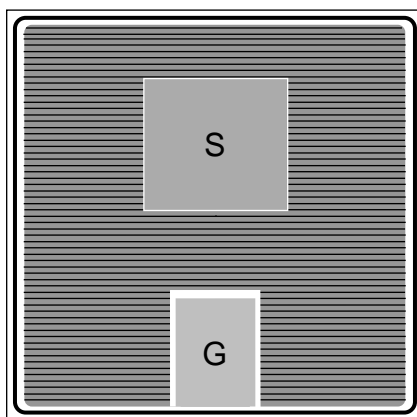


VF26



Backside: Drain

All dimensions in mils.

Die Geometry	Dimensions			Backside Metal	Bonding Pads ²		Recommended Assembly Material		
	Length ¹	Width ¹	Thickness		Material	Size	Wire ³	Wire Size ³	Preform
VF26	70	70	11 ± 1.5	Au	Al-Cu-Si	4 x 6.25	Au	1.5	Epoxy

Notes:

1. Maximum values
2. Al-Cu-Si is used for higher operating current densities. Bond pad size represents smaller gate pad.
3. Bond wire size and material depends on AuTCB, TSB or Al USB.

11/19/02